

3.3V ECL 1:2 Differential Fanout Buffer

Description

The MC100LVEL11 is a differential 1:2 fanout buffer. The device is functionally similar to the E111 device but with higher performance capabilities. Having within-device skews and output transition times significantly improved over the E111, the LVEL11 is ideally suited for those applications which require the ultimate in AC performance.

The differential inputs of the LVEL11 employ clamping circuitry to maintain stability under open input conditions. If the inputs are left open (pulled to V_{EE}) the Q outputs will go LOW.

Features

- 330 ps Propagation Delay
- 5 ps Skew Between Outputs
- High Bandwidth Output Transitions
- The 100 Series Contains Temperature Compensation
- PECL Mode Operating Range: $V_{CC} = 3.0 \text{ V}$ to 3.8 V with $V_{EE} = 0 \text{ V}$
- NECL Mode Operating Range: $V_{CC} = 0 V$ with $V_{EE} = -3.0 V$ to -3.8 V
- Internal Input Pulldown Resistors
- Q Output will Default LOW with Inputs Open or at $V_{\mbox{\scriptsize EE}}$
- Pb-Free Packages are Available

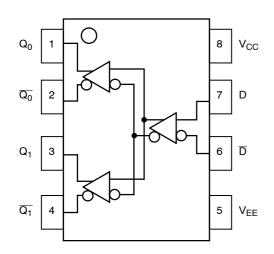
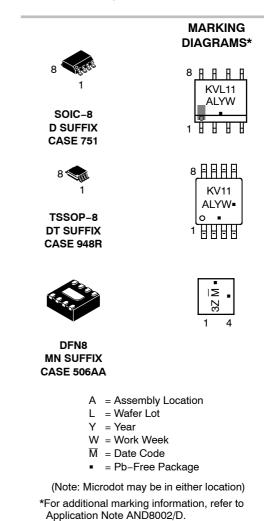


Figure 1. Logic Diagram and Pinout Assignment



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ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

查询"MC100LVEL11D 记时应用 DESCRIPTION

Pin	Function
Q0, <u>Q0</u> ; Q1, <u>Q1</u>	ECL Data Outputs
D, D	ECL Data Inputs
V _{CC}	Positive Supply
V _{EE}	Negative Supply
EP	Exposed pad must be connected to a sufficient thermal conduit. Electrically connect to the most negative supply or leave floating open.

Table 2. ATTRIBUTES

Character	Value				
Internal Input Pulldown Resistor	75 kΩ				
Internal Input Pullup Resistor	75 kΩ				
ESD Protection	Human Body Model Machine Model Charge Device Model	> 4 KV > 400 V > 2 kV			
Moisture Sensitivity, Indefinite Time	Out of Drypack (Note 1)	Level 1			
Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in			
Transistor Count	63				
Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test					

1. For additional information, see Application Note AND8003/D.

Table 3. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Units
V _{CC}	PECL Mode Power Supply	V _{EE} = 0 V		8 to 0	V
V_{EE}	NECL Mode Power Supply	$V_{CC} = 0 V$		–8 to 0	V
VI	PECL Mode Input Voltage NECL Mode Input Voltage	V _{EE} = 0 V V _{CC} = 0 V	$\begin{array}{c} V_{I} \leq V_{CC} \\ V_{I} \geq V_{EE} \end{array}$	6 to 0 –6 to 0	V
l _{out}	Output Current	Continuous Surge		50 100	mA mA
T _A	Operating Temperature Range			-40 to +85	°C
T _{stg}	Storage Temperature Range			-65 to +150	°C
θ_{JA}	Thermal Resistance (Junction-to-Ambient)	0 lpfm 500 lpfm	SOIC-8 SOIC-8	190 130	°C/W °C/W
θ_{JC}	Thermal Resistance (Junction-to-Case)	Standard Board	SOIC-8	41 to 44 ± 5%	°C/W
θ_{JA}	Thermal Resistance (Junction-to-Ambient)	0 lpfm 500 lpfm	TSSOP-8 TSSOP-8	185 140	°C/W °C/W
θ_{JC}	Thermal Resistance (Junction-to-Case)	Standard Board	TSSOP-8	41 to 44 ± 5%	°C/W
θ_{JA}	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	DFN8 DFN8	129 84	°C/W °C/W
T _{sol}	Wave Solder Pb Pb-Free	<2 to 3 sec @ 248°C <2 to 3 sec @ 260°C		265 265	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

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			−40°C		25°C		85°C				
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
I _{EE}	Power Supply Current		24	28		24	28		25	30	mA
V _{OH}	Output HIGH Voltage (Note 3)	2215	2295	2420	2275	2345	2420	2275	2345	2420	mV
V _{OL}	Output LOW Voltage (Note 3)		1605	1745	1490	1595	1680	1490	1595	1680	mV
V _{IH}	Input HIGH Voltage (Single-Ended)	2135		2420	2135		2420	2135		2420	mV
V _{IL}	Input LOW Voltage (Single-Ended)	1490		1825	1490		1825	1490		1825	mV
V _{IHCMR}	Input HIGH Voltage Common Mode Range (Differential) (Note 7) $ \begin{array}{c} V_{pp} < 500 \text{ mV} \\ V_{pp} \geqq 500 \text{ mV} \end{array} $	1.2 1.4		3.1 3.1	1.1 1.3		3.1 3.1	1.1 1.3		3.1 3.1	v v
I _{IH}	Input HIGH Current			150			150			150	μA
IIL	Input LOW Current D	0.5 -600			0.5 -600			0.5 -600			μΑ μΑ

Table M LYRECL DC CHARACTERISTICS VCC = 3.3 V; VFF = 0.0 V (Note 2)

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

2. Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary ±0.3 V.

3. Outputs are terminated through a 50 Ω resistor to \overline{V}_{CC} – 2.0 V.

4. V_{IHCMR} min varies 1:1 with V_{EE}, max varies 1:1 with V_{CC}. The V_{IHCMR} range is referenced to the most positive side of the differential input signal. Normal operation is obtained if the HIGH level falls within the specified range and the peak-to-peak voltage lies between Vppmin and 1.0 V.

			-40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
I _{EE}	Power Supply Current		24	28		24	28		25	30	mA
V _{OH}	Output HIGH Voltage (Note 6)	-108 5	-100 5	-880	-102 5	-955	-880	-102 5	-955	-880	mV
V _{OL}	Output LOW Voltage (Note 6)	-183 0	-169 5	-155 5	-181 0	-170 5	-162 0	-181 0	-170 5	-162 0	mV
V _{IH}	Input HIGH Voltage (Single-Ended)	-1165		-880	-1165		-880	-1165		-880	mV
V _{IL}	Input LOW Voltage (Single-Ended)	-181 0		-147 5	-181 0		-147 5	-181 0		-147 5	mV
V _{IHCMR}	Input HIGH Voltage Common Mode Range (Differential) (Note 7) $V_{pp} < 500 \text{ mV}$ $V_{pp} \ge 500 \text{ mV}$	-2.1 -1.9		-0.2 -0.2	-2.2 -2.0		-0.2 -0.2	-2.2 -2.0		-0.2 -0.2	v v
I _{IH}	Input HIGH Current			150			150			150	μA
IIL	Input LOW Current D	0.5 -600			0.5 -600			0.5 -600			μΑ μΑ

Table 5. LVNECL DC CHARACTERISTICS $V_{CC} = 0.0 \text{ V}; V_{EE} = -3.3 \text{ V}$ (Note 5)

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

5. Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary \pm 0.3 V.

6. Outputs are terminated through a 50 Ω resistor to V_{CC} – 2.0 V. 7. V_{IHCMR} min varies 1:1 with V_{EE}, max varies 1:1 with V_{CC}. The V_{IHCMR} range is referenced to the most positive side of the differential input signal. Normal operation is obtained if the HIGH level falls within the specified range and the peak-to-peak voltage lies between V_{PP}min and 1.0 V.

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		–40°C		25°C			85°C				
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
f _{max}	Maximum Toggle Frequency					1.0					GHz
t _{PLH} t _{PHL}	Propagation Delay to Output	235		385	255	330	405	285		435	ps
t _{SKEW}	Within-Device Skew (Note 9) Device-to-Device (Note 10) Duty Cycle Skew (Note 11)		5 10	20 150 20		5 10	20 150 20		5 10	20 150 20	ps
t _{JITTER}	Random Clock Jitter (RMS)					0.6					ps
V_{PP}	Input Swing (Note 12)	200		1000	200	1000		200	1000		mV
t _r t _f	Output Rise/Fall Times Q (20% – 80%)	120		320	120	220	320	120		320	ps

Table 6. AC CHARACTERISTICS $V_{CE} = 3.3 \text{ V}; \text{ V}_{EE} = 0.0 \text{ V} \text{ or } \text{ V}_{CC} = 0.0 \text{ V}; \text{ V}_{EE} = -3.3 \text{ V} (Note 8)$

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

8. V_{EE} can vary ±0.3 V.

9. Within-device skew defined as identical transitions on similar paths through a device.

10. Device-to-device skew for identical transitions at identical V_{CC} levels.

11. Duty cycle skew is the difference between a t_{PLL} and t_{PLL} propagation delay through a device.

12. V_{PP}(min) is the minimum input swing for which AC parameters guaranteed. The device will function properly with input swings below 200 mV, however, AC delays may move outside of the specified range. The device has a DC gain of ≈40.

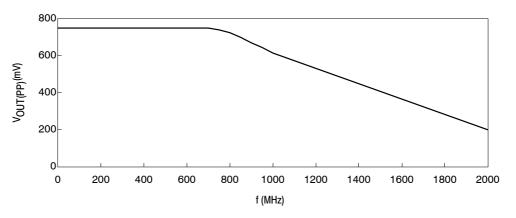


Figure 2. Output Swing versus Frequency

Device	Package	Shipping [†]
MC100LVEL11D	SOIC-8	98 Units / Rail
MC100LVEL11DG	SOIC-8 (Pb-Free)	98 Units / Rail
MC100LVEL11DR2	SOIC-8	2500 Tape & Reel
MC100LVEL11DR2G	SOIC–8 (Pb–Free)	2500 Tape & Reel
MC100LVEL11DT	TSSOP-8	100 Units / Rail
MC100LVEL11DTG	TSSOP-8 (Pb-Free)	100 Units / Rail
MC100LVEL11DTR2	TSSOP-8	2500 Tape & Reel
MC100LVEL11DTR2G	TSSOP-8 (Pb-Free)	2500 Tape & Reel
MC100LVEL11MNR4	DFN8	1000 / Tape & Reel
MC100LVEL11MNR4G	DFN8 (Pb–Free)	1000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

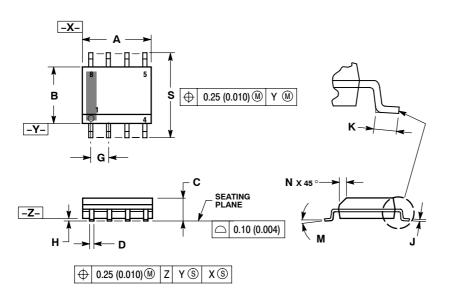
Resource Reference of Application Notes

AN1405/D	-	ECL Clock Distribution Techniques
AN1406/D	-	Designing with PECL (ECL at +5.0 V)
AN1503/D	-	ECLinPS [™] I/O SPiCE Modeling Kit
AN1504/D	-	Metastability and the ECLinPS Family
AN1568/D	-	Interfacing Between LVDS and ECL
AN1672/D	-	The ECL Translator Guide
AND8001/D	-	Odd Number Counters Design
AND8002/D	_	Marking and Date Codes
AND8020/D	-	Termination of ECL Logic Devices
AND8066/D	-	Interfacing with ECLinPS
AND8090/D	_	AC Characteristics of ECL Devices

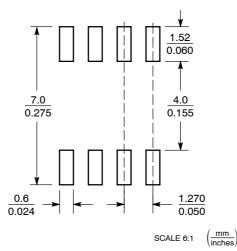
查询"MC100LVEL11DG"供应商

PACKAGE DIMENSIONS

SOIC-8 NB CASE 751-07 **ISSUE AH**



SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

- NOTES:
 DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: MILLIMETER.
 DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
 MAXIMUM MOLD PROTRUSION 0.15 (0.006) DEB SIDE

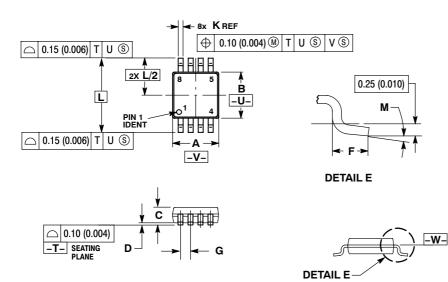
- MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
 DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
 751-01 THRU 751-06 ARE OBSOLETE. NEW STANDARD IS 71 07
- STANDARD IS 751-07.

	MILLIN	IETERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	4.80	5.00	0.189	0.197	
В	3.80	4.00	0.150	0.157	
С	1.35	1.75	0.053	0.069	
D	0.33	0.51	0.013	0.020	
G	1.27	7 BSC	0.050 BSC		
н	0.10	0.25	0.004	0.010	
J	0.19	0.25	0.007	0.010	
к	0.40	1.27	0.016	0.050	
м	0 °	8 °	0 °	8 °	
Ν	0.25	0.50	0.010	0.020	
S	5.80	6.20	0.228	0.244	

PACKAGE DIMENSIONS

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TSSOP-8 DT SUFFIX PLASTIC TSSOP PACKAGE CASE 948R-02 **ISSUE A**



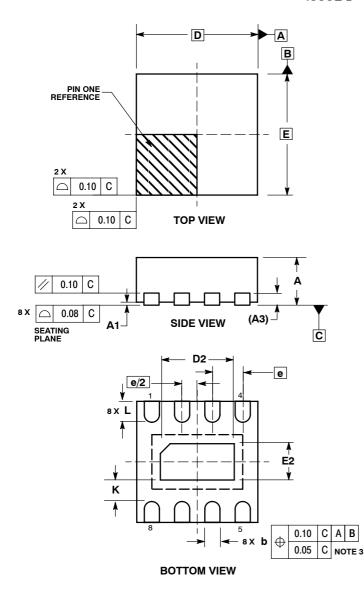
- NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETER.
- DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15
- GATE DOINS SHALL NOT EXCEED 0.13
 (0.006) PER SIDE.
 DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) DED SIDE PER SIDE. 5. TERMINAL NUMBERS ARE SHOWN FOR
- REFERENCE ONLY.
 DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

	MILLIN	IETERS	INCHES			
DIM	MIN	MAX	MIN	MAX		
Α	2.90	3.10	0.114	0.122		
В	2.90	3.10	0.114	0.122		
С	0.80	1.10	0.031	0.043		
D	0.05	0.15	0.002	0.006		
F	0.40	0.70	0.016	0.028		
G	0.65	BSC	0.026	BSC		
K	0.25	0.40	0.010	0.016		
L	4.90	BSC	0.193 BSC			
М	0°	6 °	0°	6°		

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PACKAGE DIMENSIONS

DFN8 CASE 506AA-01 ISSUE D



NOTES:

 DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 CONTROLLING DIMENSION: MILLIMETERS.

 DIMENSION & APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN
 O SAND O SO MM EPOM TERMINAL

0.25 AND 0.30 MM FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIMETERS					
DIM	MIN	MAX				
Α	0.80	1.00				
A1	0.00	0.05				
A3	0.20	REF				
b	0.20	0.30				
D	2.00	BSC				
D2	1.10	1.30				
E	2.00	BSC				
E2	0.70	0.90				
е	0.50	BSC				
к	0.20					
L	0.25	0.35				

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